

Electronic Patent Application Fee Transmittal				
Application Number:		10511566		
Filing Date:		13-Apr-2005		
Title of Invention:		PROCESS OF VAPOR DEPOSITING GLASS LAYERS FOR WAFER-LEVEL HERMETIC ENCAPSULATION OF ELECTRONIC MODULES		
First Named Inventor/Applicant Name:		Jurgen Leib		
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Attorney Docket Number:		2133.063USU		
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
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Utility Appl issue fee	1501	1	1510	1510
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